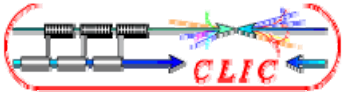


# CLIC workshop "Two beam hardware and integration" working group

## Main requirement for module cooling

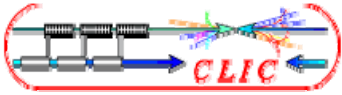
Risto Nousiainen

17.10.2007



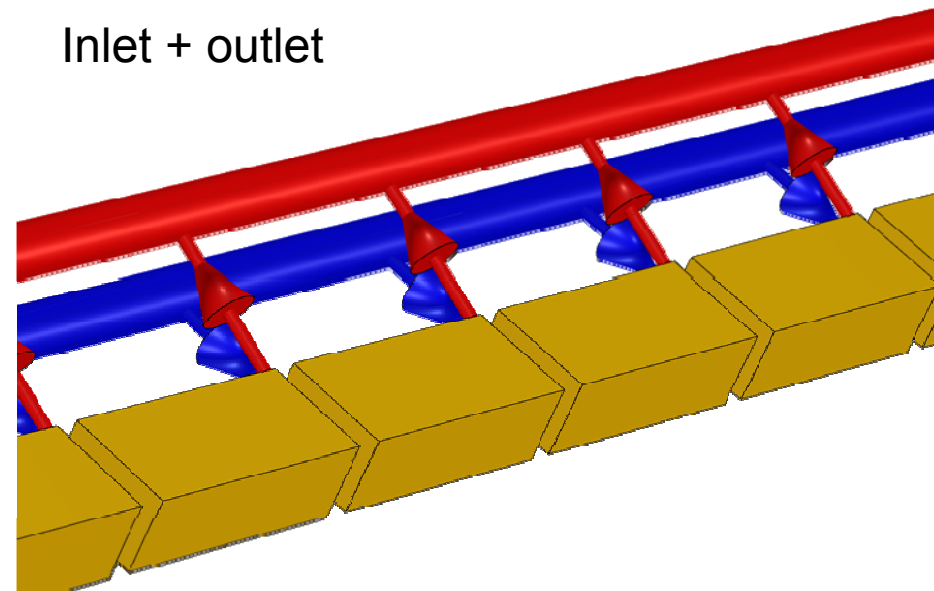
# Introduction

- Baseline for the cooling
- Main components
- Boundaries / objectives for cooling
- Possible layouts for module cooling
- Cooling concepts for accelerating structure
- Discussion
- Future work



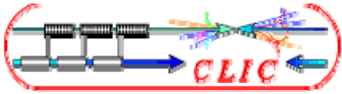
# Baseline

- 10275 modules in a one linac
- Modules cooled in parallel
- One cooling sector 4.8 km
- Water cooling



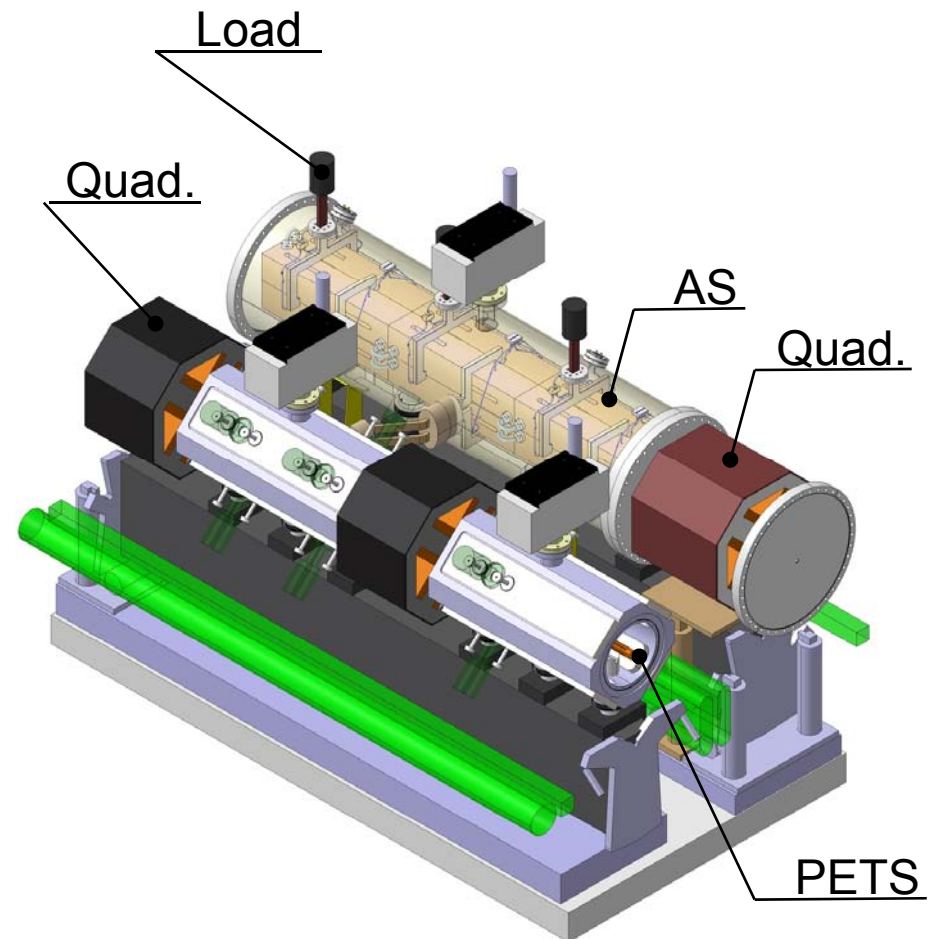
Inlet + outlet

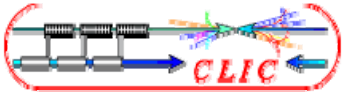
Modules



# Main components

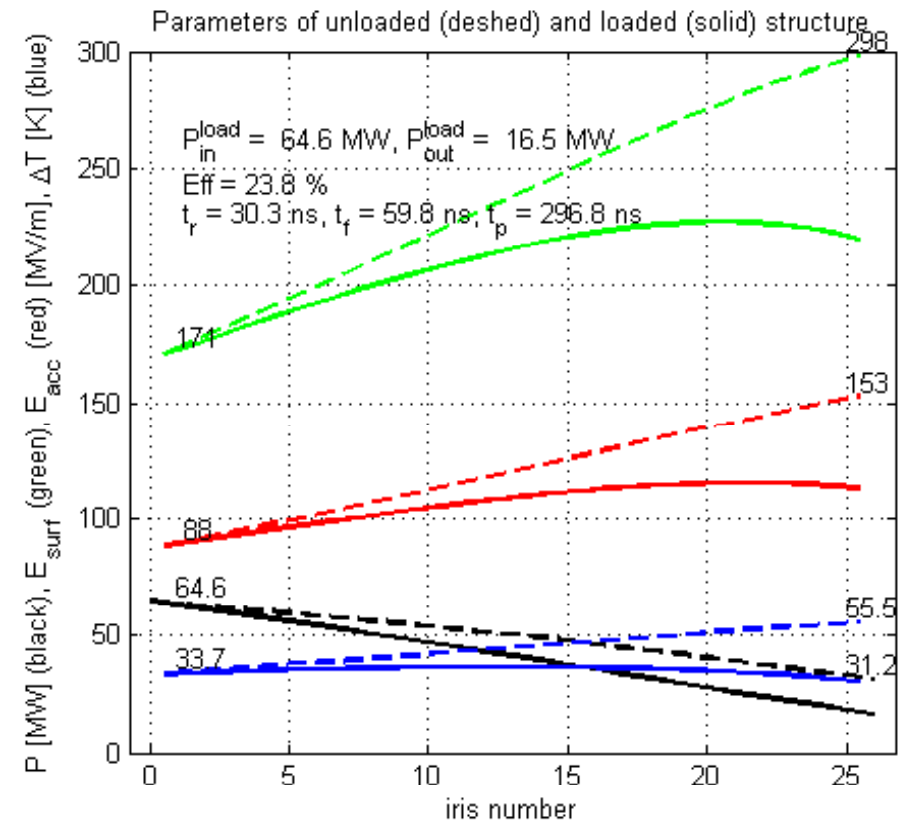
- Order of magnitudes:
- Thermal load of a one structure
  - AS ~ 550 W
  - PETS ~ 110 W
- Thermal load of a standard module ~ 7.7 kW
- Thermally sensitive components:
  - AS
  - (PETS)
- Conventional cooling:
  - Loads
  - Quadrupoles

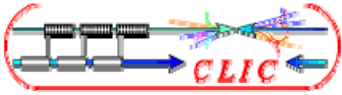




# Boundaries / objectives

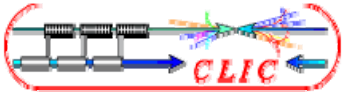
- Tight alignment tolerances
  - Micron level requirement for AS
- Tight thermal requirements
  - +/- 0.1 K ( $1\sigma$ ) stability
- Beam energy levels
  - From 0.5 TeV to 3 TeV
  - Affects on thermal load
- Loaded and Unloaded case
  - Different thermal load





# Cooling induced effects

- Thermal:
  - Alignment errors due to thermal expansion
    - Static → Predictable: operational temperature, longitudinal elongation, transverse elongation
    - **Dynamic** → Unpredictable: water temperature instability, RF power variation
  - Temperature dependent RF behavior
    - Phase error (mainly for AS)
- Mechanical
  - Fluid induced vibrations

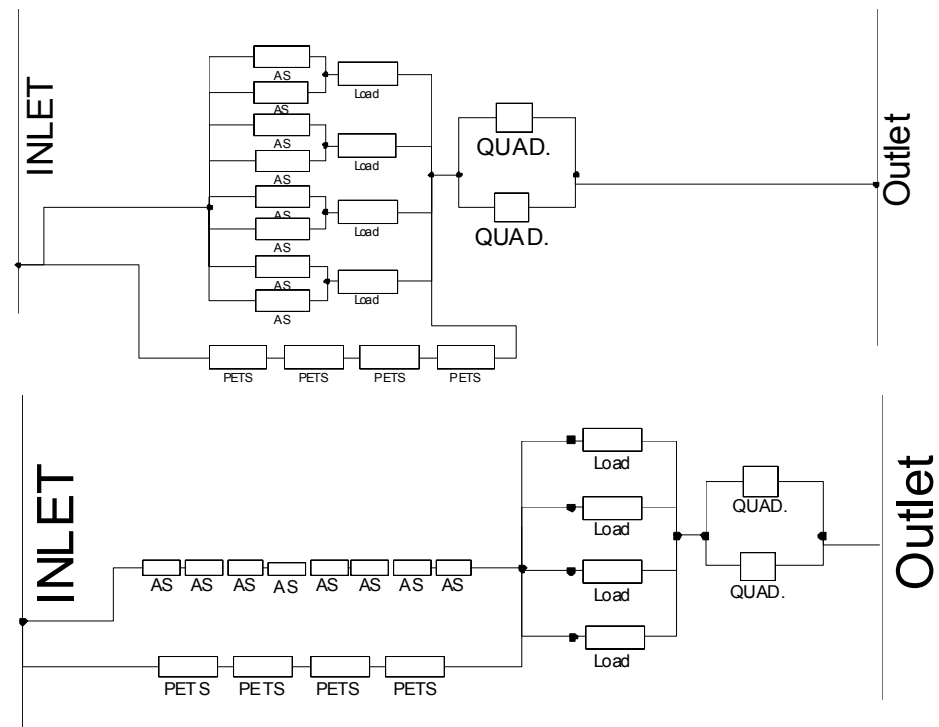


# Layouts for module cooling

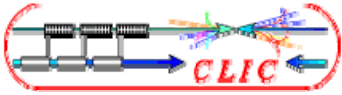
Configuration	-	+	$V_{\text{flow module}}$	$V_{\text{flow sector}}$
AS Parallel	Additional volumetric flow	Thermal stability Temperature gradient	$3 \text{ m}^3/\text{hr}$	$7500 \text{ m}^3/\text{hr}$
AS Series	8 different structures Thermal stability	Small volumetric flow High $\Delta T$ of water	$0,5 \text{ m}^3/\text{hr}$	$1200 \text{ m}^3/\text{hr}$

- Two extreme cases
- Other options:
  - Two AS in series

$\Delta T$  over one AS 1.5 K



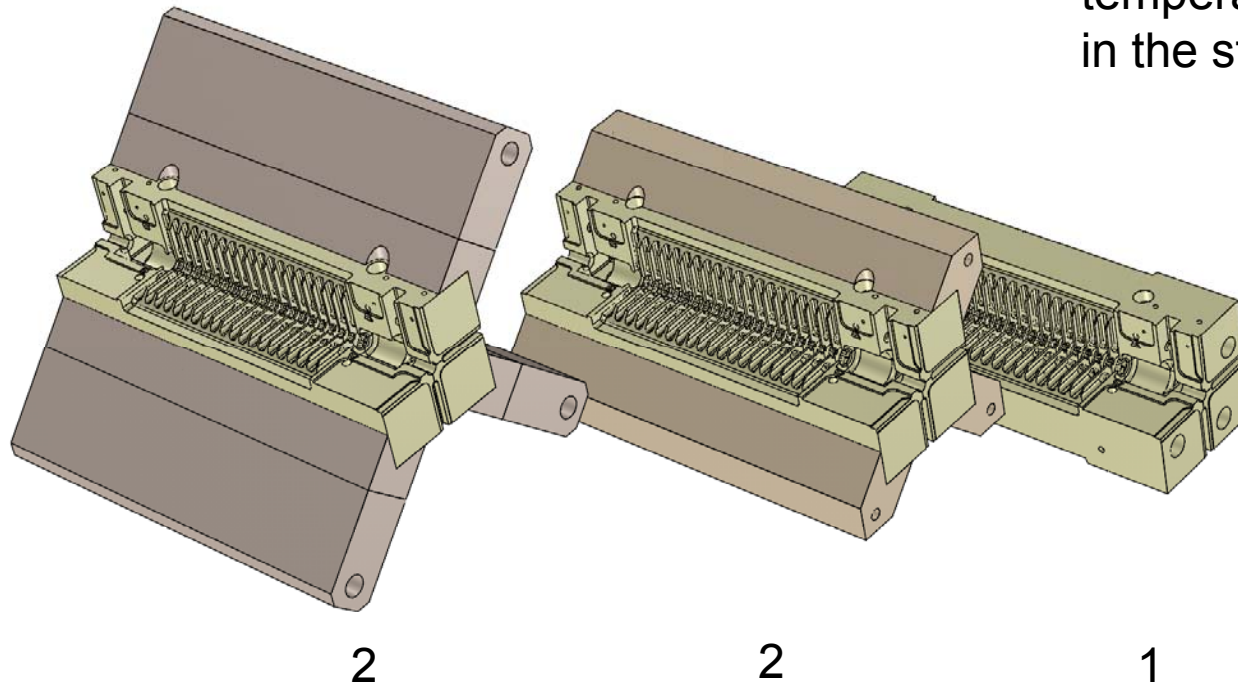
NB: For a standard module.



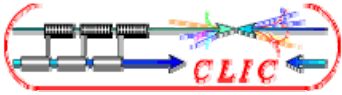
# Cooling concepts for AS

1. Convection cooling
2. Conduction cooling

Objective: Minimize the temperature gradient in the structure







# Discussion

- Main issues:

- 1. Tolerances

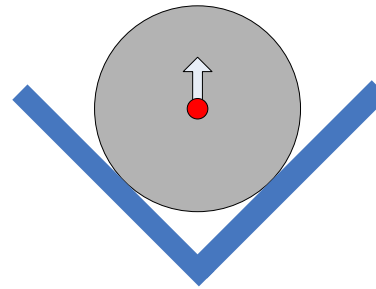
- Static
- Dynamic

- 2. Vibrations

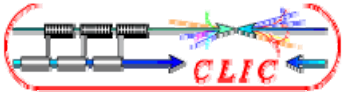
- Water induced
- Balance between sufficient cooling and acceptable flow parameters

- 3. Temperature stabilization

- 4. Volumetric flow



1 Kelvin causes an misalignment of 7 microns with the current support



# Future work

- Previous study:
  - Water induced Quadrupole vibrations
- Future work
  - How to compensate dynamic effects?
  - How to predict water induced vibrations?
  - System design for cooling